Author Index

Bachur, Gerald, *Development of Optical Measurement and Control Systems for Photolithography,* **2**
Brixner, Berlyn, *Simple Step-and-Repeat Precision Copy Camera,* **34**
Christian, Michael, *Simple Step-and-Repeat Precision Copy Camera,* **34**
Darley, H. M., *Submicron X-Ray Lithography,* **100**
DePuy, A. H., *Masking with Matched Sets,* **80**
Duville, R., *Improved Microphotographic Systems in the Semiconductor Industry,* **39**
George, Nicholas, *Linewidth Measurement by Diffraction Pattern Analysis,* **54**
Guterman, D. C., *Submicron X-Ray Lithography,* **100**
Habegger, M. A., *Optical Determination of Semiconductor Device Edge Profiles,* **95**
Hasemann, Herb G., *Photomasks for Micron Geometry Transistors,* **140**
Huck, Friedrich O., *Viking Lander Camera—Performance Characteristics and Data Reduction Techniques,* **109**
Jacoby, Hans-Dieter, *New Approaches for High Repeatibility Mask Making and Mask Measuring,* **130**
Jerke, John M., *Effects of Operating Parameters on Line-Width Measurements with an Optical Microscope,* **64**
Kasdan, Harvey L., *Linewidth Measurement by Diffraction Pattern Analysis,* **54**
Koch, James K., *Laser Interferometers in Microlithography,* **112**
Long, Franklin L., *Photomask Inspection Techniques for Predicting and Maximizing LSI Yield,* **121**
Long, Mary L., *Photomask Inspection Techniques for Predicting and Maximizing LSI Yield,* **121**
McCall, Henry, *Viking Lander Camera,* **108**
Novotny, Donald B., *Photoresist Exposure—Measurement and Control,* **9**
Nyyssonen, Diana, *Effects of Operating Parameters on Line-Width Measurements with an Optical Microscope,* **64**
Paterson, K. H., *Evaluation of Photomask Materials and Their Effect on Yield,* **47**
Penninger, Robert, *Viking Ground Reconstruction Equipment,* **110**
Philippaerts, H., *Improved Microphotographic Systems in the Semiconductor Industry,* **39**
Pratt, Wayne R., *Photomask Degradation in Contact Printing of LSI Circuits onto Silicon Wafers,* **126**
Risen, M. P., *Photomask Degradation in Contact Printing of LSI Circuits onto Silicon Wafers,* **126**
Rosenthal, Richard A., *Evaluation of Rank Prismatic Lens,* **18**
Rottman, H. R., *Dry Cleaning of 10X Masks,* **28**
Shoho, Reynold M., *Problems Associated with Photomask Production,* **138**
Stelter, M. K., *Evaluation of Photomask Materials and Their Effect on Yield,* **47**
Swing, Richard E., *Theoretical Basis of a New Optical Method for the Accurate Measurement of Small Line-Widths,* **65**
Underhill, J. A., *Overlay Precision for Micron Lithography,* **85**
Vanassche, W., *Improved Microphotographic Systems in the Semiconductor Industry,* **39**
Van De Ven, Jaimie, *Obtaining a Mask Set—From a User's Point of View,* **142**
Watts, R. K., *Submicron X-Ray Lithography,* **100**
Widigen, Larry, *Artwork Mask Generation of Convex/Concave Regions,* **22**
Wright, Mel, *Mask Inspection—What's It Worth to You?,* **137**

Subject Index

Accurate measurement of small linewidths, theoretical basis of new optical method for, 65
Analysis, linewidth measurement by diffraction pattern, 54
Approaches for high repeatibility mask making and mask measuring, new, 130
Artwork mask generation of convex/concave regions, 22

Basis of new optical method for accurate measurement of small linewidths, theoretical, 65

Camera—performance characteristics and data reduction techniques, Viking Lander, 109
Camera, simple step-and-repeat precision copy, 34
Camera, Viking Lander, 108
Characteristics and data reduction techniques, Viking Lander camera—performance, 109
Circuits onto silicon wafers, photomask degradation contact printing of LSI, 126
Cleaning of 10X masks, dry, 28
Concave regions, artwork mask generation of convex/, 22
Contact printing of LSI circuits onto silicon wafers, photomask degradation, 126
Control, photoresist exposure—measurement and, 9
Control systems for photolighography, development of optical measurement and, 2
Convex/concave regions, artwork mask generation of, 22
Copy camera, simple step-and-repeat precision, 34

Data reduction techniques, Viking Lander camera—performance characteristics and, 109
Degradation in contact printing of LSI circuits onto silicon wafers, photomask, 126
Determination of semiconductor device edge profiles, optical, 95
Development of optical measurement and control systems for photolithography, 2
Device edge profiles, optical determination of semiconductor, 95
Diffraction pattern analysis, linewidth measurement by, 54
Dry cleaning of 10X masks, 28

Edge profiles, optical determination of semiconductor device, 95
Effects of operating parameters on linewidth measurements with an optical microscope, 64
Equipment, Viking ground reconstruction, 110
Evaluation of photomask materials and their effect on yield, 47
Evaluation of rank prismatic lens, 18
Exposure—measurement and control, photoresist, 9

Generation of convex/concave regions, artwork mask, 22
Geometry transistors, photomasks for micron, 140
Ground reconstruction equipment, Viking, 110

High repeatibility mask making and mask measuring, new approaches for, 130

Improved microphotographic systems in the semiconductor industry, 39
Industry, improved microphotographic systems in the semiconductor, 39
Inspection and measurement technology requirements, 136
Inspection techniques for predicting and maximizing LSI yield, photomask, 121
Inspection—what's it worth to you?, mask, 137
Interferometers in microlithography, laser, 112

Lander camera—performance characteristics and data reduction techniques, Viking, 109
Lander camera, Viking, 108
Laser interferometers in microlithography, 112
Lens, evaluation of Rank prismatic, 18
Linewidth measurement by diffraction pattern analysis, 54
Linewidth measurements with an optical microscope, effects of operating parameters on, 64
Linewidths, theoretical basis of new optical method for accurate measurement of small, 65
Lithography, overlay precision for micron, 85
Lithography, submicron X-ray, 100
LSI circuits onto silicon wafers, photomask degradation contact printing of, 126
LSI yield, photomask inspection techniques for predicting and maximizing, 121

Mask generation of convex/concave regions, artwork, 22
Mask inspection—what's it worth to you?, 137
Mask making and mask measuring, new approaches for high repeatibility, 130
Mask set—from a user's point of view, obtaining a, 142
Masking with matched sets, 80
Masks, dry cleaning of 10X, 28
Matched sets, masking with, 80
Materials and their effect on yield, evaluation of photomask, 47
Maximizing LSI yield, photomask inspection techniques for predicting and, 121
Measurement and control, photoresist exposure—, 9
Measurement and control systems for photolithography, development of optical, 2
Measurement by diffraction pattern analysis, linewidth, 54
Measurement of small linewidths, theoretical basis of new optical method for accurate, 65
Measurement technology requirements, inspection and, 136
Measurements with an optical microscope, effects of operating parameters on linewidth, 64
Method for accurate measurement of small linewidths, theoretical basis of new optical, 65
Microlithography, laser interferometers in, 112
Micron geometry transistors, photomasks for, 140
Micron lithography, overlay precision for, 85
Microphotographic systems in the semiconductor industry, improved, 39
Microscope, effects of operating parameters on linewidth measurements with an optical, 64

New approaches for high repeatibility mask making and mask measuring, 130
New optical method for accurate measurement of small linewidths, theoretical basis of, 65

Obtaining a mask set—from a user's point of view, 142
Operating parameters on linewidth measurements with an optical microscope, effects of, 64
Optical determination of semiconductor device edge profiles, 95
Optical measurement and control systems for photolithography, development of, 2
Optical method for accurate measurement of small linewidths, theoretical basis of new, 65
Optical microscope, effects of operating parameters on linewidth measurements with an, 64
Overlay precision for micron lithography, 85

Parameters on linewidth measurements with an optical microscope, effects of operating, 64
Pattern analysis, linewidth measurement by diffraction, 54
Performance characteristics and data reduction techniques, Viking Lander camera—, 109
Photolithography, development of optical measurement and control systems for, 2
Photomask degradation in contact printing of LSI circuits onto silicon wafers, 126
Photomask inspection techniques for predicting and maximizing LSI yield, 121
Photomask materials and their effect on yield, evaluation of, 47
Photomask production, problems associated with, 138
Photomasks for micron geometry transistors, 140
Photoresist exposure—measurement and control, 9
Precision copy camera, simple step-and-repeat, 34
Precision for micron lithography, overlay, 85
Predicting and maximizing LSI yield, photomask inspection techniques for, 121
Printing of LSI circuits onto silicon wafers, photomask degradation contact, 126
Prismatic lens, evaluation of Rank, 18
Problems associated with photomask production, 138
Production, problems associated with photomask, 138
Profiles, optical determination of semiconductor device edge, 95

Rank prismatic lens, evaluation of, 18
Reconstruction equipment, Viking ground, 110
Reduction techniques, Viking Lander camera—performance characteristics and data, 109
Regions, artwork mask generation of convex/concave, 22
Repeat precision copy camera, simple step-and-, 34
Repeatibility mask making and mask measuring, new approaches for high, 130
Requirements, inspection and measurement technology, 136

Semiconductor device edge profiles, optical determination of, 95
Semiconductor industry, improved microphotographic systems in the, 39
Sets, masking with matched, 80
Silicon wafers, photomask degradation contact printing of LSI circuits onto, 126
Simple step-and-repeat precision copy camera, 34
Small linewidths, theoretical basis of new optical method for accurate measurement of, 65
Step-and-repeat precision copy camera, simple, 34
Submicron X-ray lithography, 100
Systems for photolithography, development of optical measurement and control, 2
Systems in the semiconductor industry, improved microphotographic, 39

Techniques for predicting and maximizing LSI yield, photomask inspection, 121
Techniques, Viking Lander camera—performance characteristics and data reduction, 109
Technology requirements, inspection and measurement, 136
10X masks, dry cleaning of, 28
Theoretical basis of a new optical method for the accurate measurement of small linewidths, 65
Transistors, photomasks for micron geometry, 140

User's point of view, obtaining a mask set—from a, 142

Viking ground reconstruction equipment, 110
Viking Lander camera, 108
Viking Lander camera—performance characteristics and data reduction techniques, 109

Wafers, photomask degradation contact printing of LSI circuits onto silicon, 126

X-ray lithography, submicron, 100
Yield, evaluation of photomask materials and their effect on, 47